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|                                               |                   |
|   SYSTEM DIAGRAMS                             |  CHAPTER   8      |
|                                               |                   |
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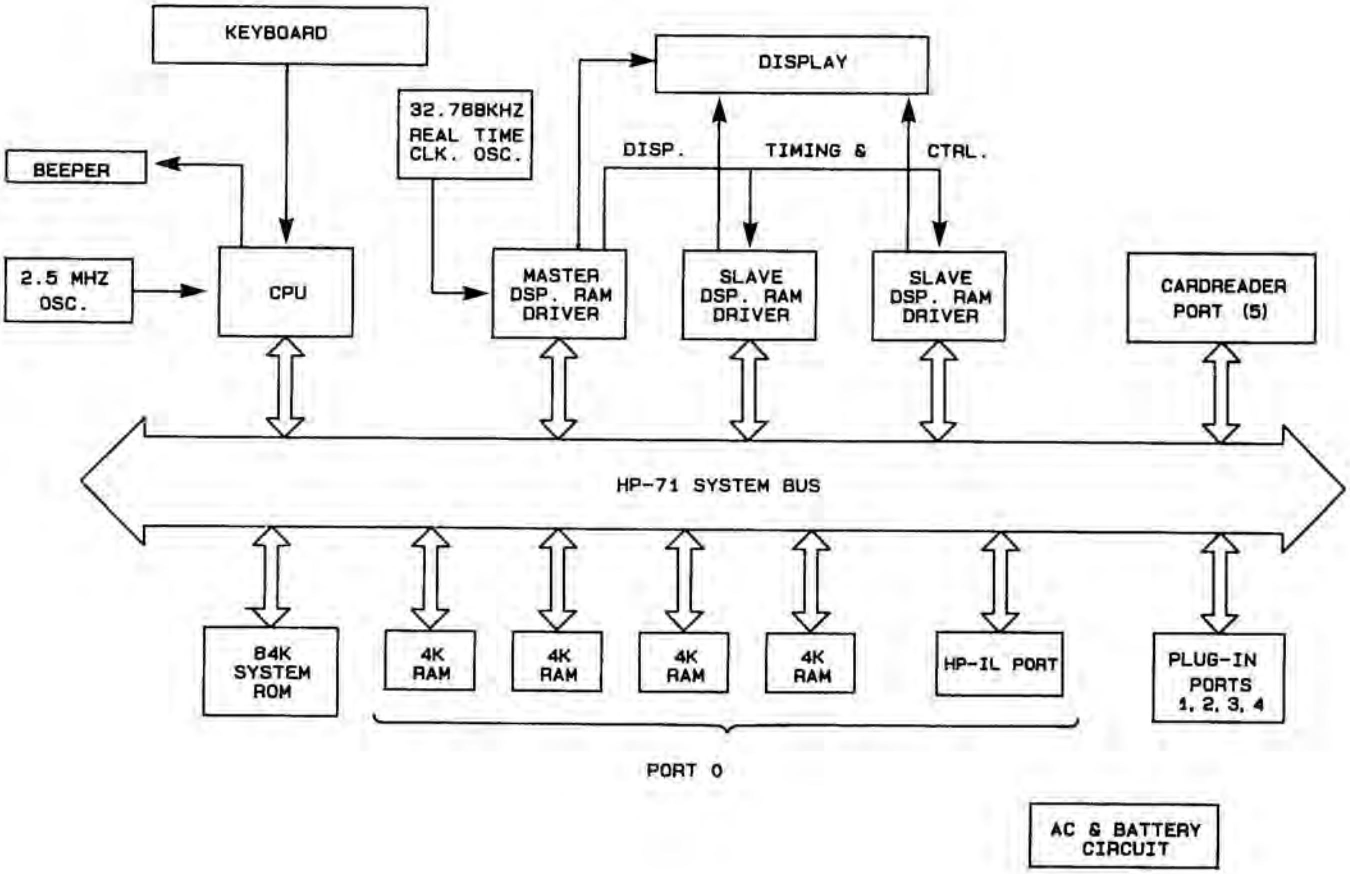


Figure 8-1. System Block Diagram

Table 8-1. Top-Case Assembly Replaceable Parts

INDEX NUMBER, FIGURE 7-1	HP PART NUMBER	DESCRIPTION	QUANTITY
C4,C5	0160-5789	CAPACITOR, 33 pF, 50V, 5%	2
C6,C7	0160-5790	CAPACITOR, 0.1 uF, 25V, 20%	2
C9,C10	0160-5787	CAPACITOR, 1000 pF, 5V, 20%	2
C11,C14	0160-5788	CAPACITOR, 220 pF,±5%	2
L1	9140-0802	INDUCTOR, 180 uH, 5%	1
R20,R21	0699-1141	RESISTOR, 10K, 5%, 1/8W	2
Y1	0410-1381	CRYSTAL, quartz	1

Table 8-2. I/O Assembly Replaceable Parts

INDEX NUMBER, FIGURE 7-2	HP PART NUMBER	DESCRIPTION	QUANTITY
C1	0180-3351	CAPACITOR, 470 uF, 10V, 20%	1
C2	0180-3352	CAPACITOR, 330 uF, 16V, 20%	1
C8	0160-0576	CAPACITOR, 0.1 uF, 50V, 20%	1
C12	0160-3879	CAPACITOR, 0.01 uF, 20%	1
C13	0160-4441	CAPACITOR, 0.47 uF, 10%	1
CR2	1901-0999	DIODE, Schottky	1
CR3	1906-0069	DIODE, bridge, full-wave, 400V	1
CR7	1901-0704	RECTIFIER, silicon	4
L2	9140-0794	INDUCTOR, 56 mH, 10%	1
Q1	1854-0932	TRANSISTOR, NPN	1
Q2	1854-0973	TRANSISTOR,	1
R22	0683-3915	RESISTOR, 390 ohms, 5%, 0.25W	1
R23,R24	0683-1035	RESISTOR, 10 K-ohms, 5%, 0.25W	2
VR7	1902-1390	DIODE, Zener	1

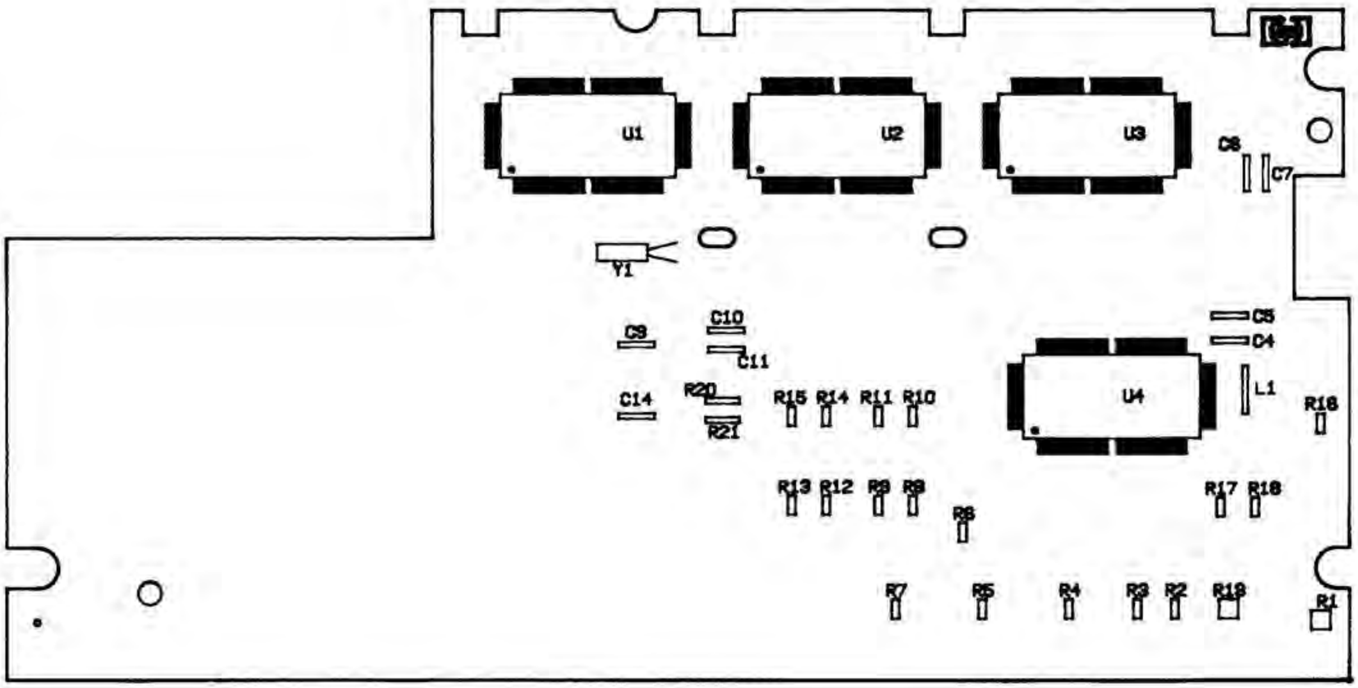
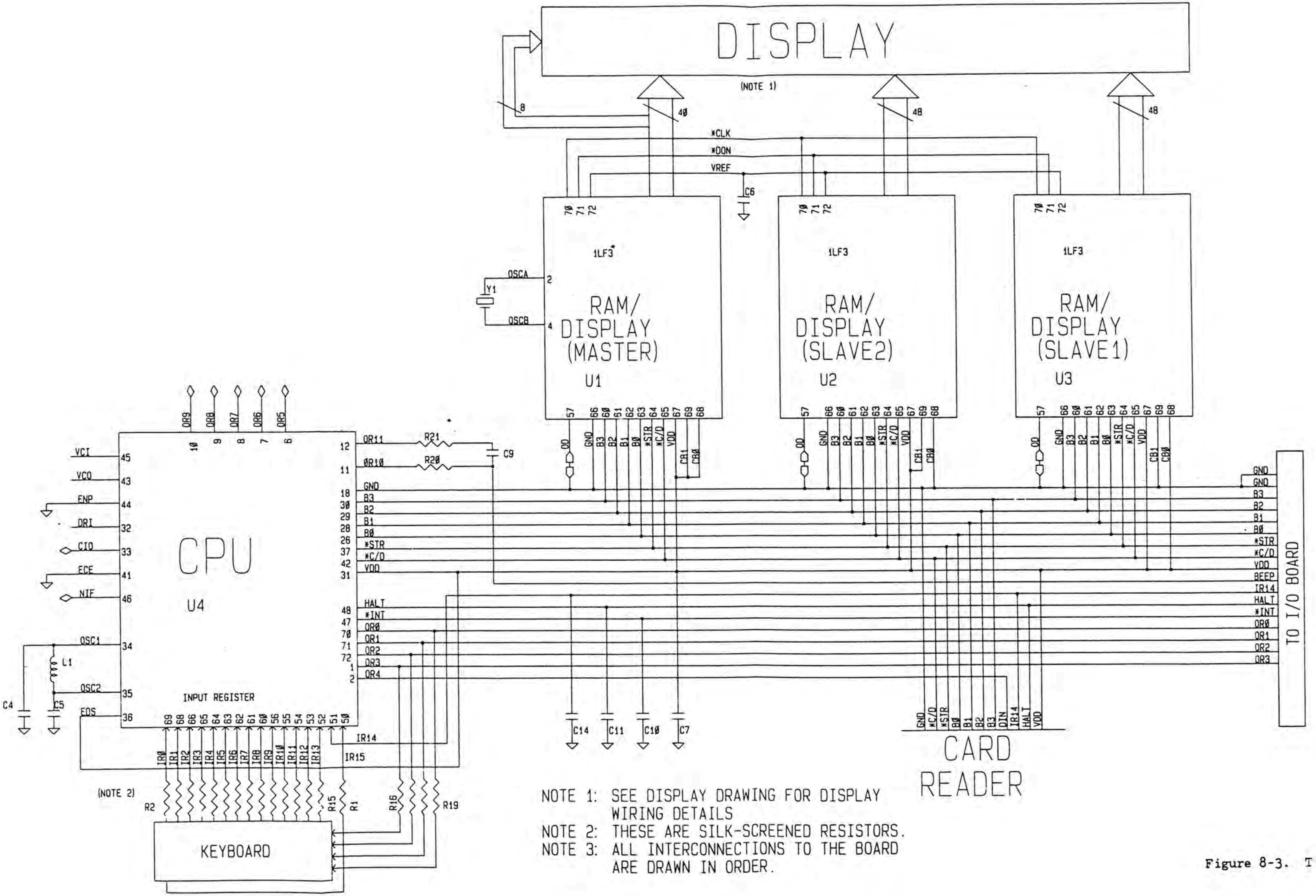


Figure 8-2. Top-case Assembly Component Location Diagram



NOTE 1: SEE DISPLAY DRAWING FOR DISPLAY WIRING DETAILS

NOTE 2: THESE ARE SILK-SCREENED RESISTORS.

NOTE 3: ALL INTERCONNECTIONS TO THE BOARD ARE DRAWN IN ORDER.

Figure 8-3. T

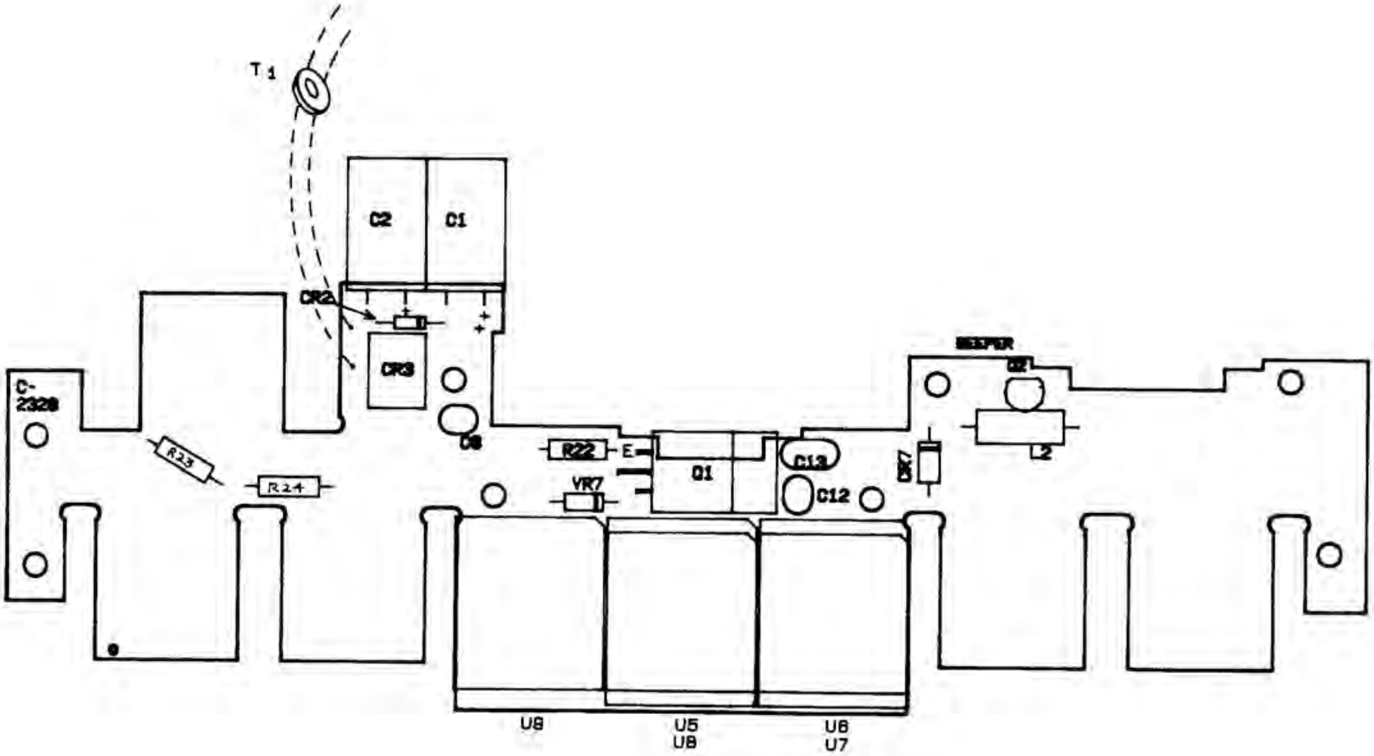
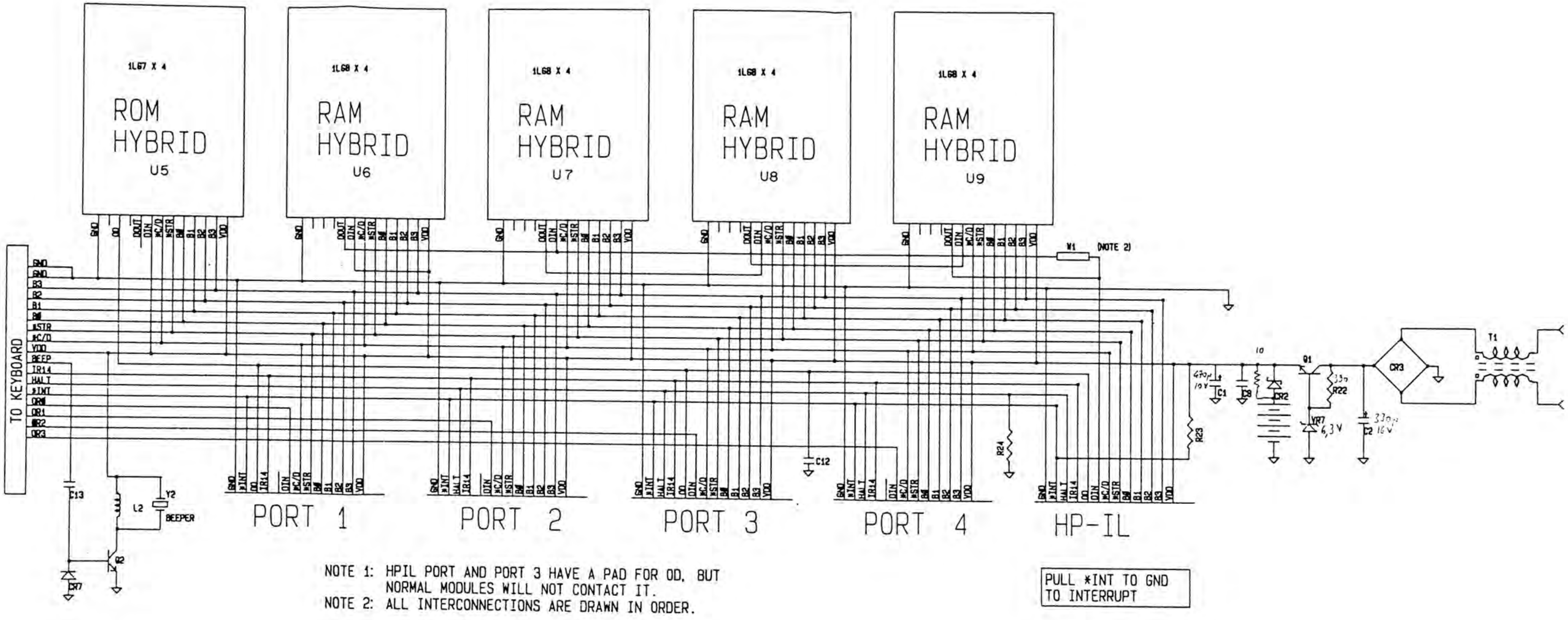


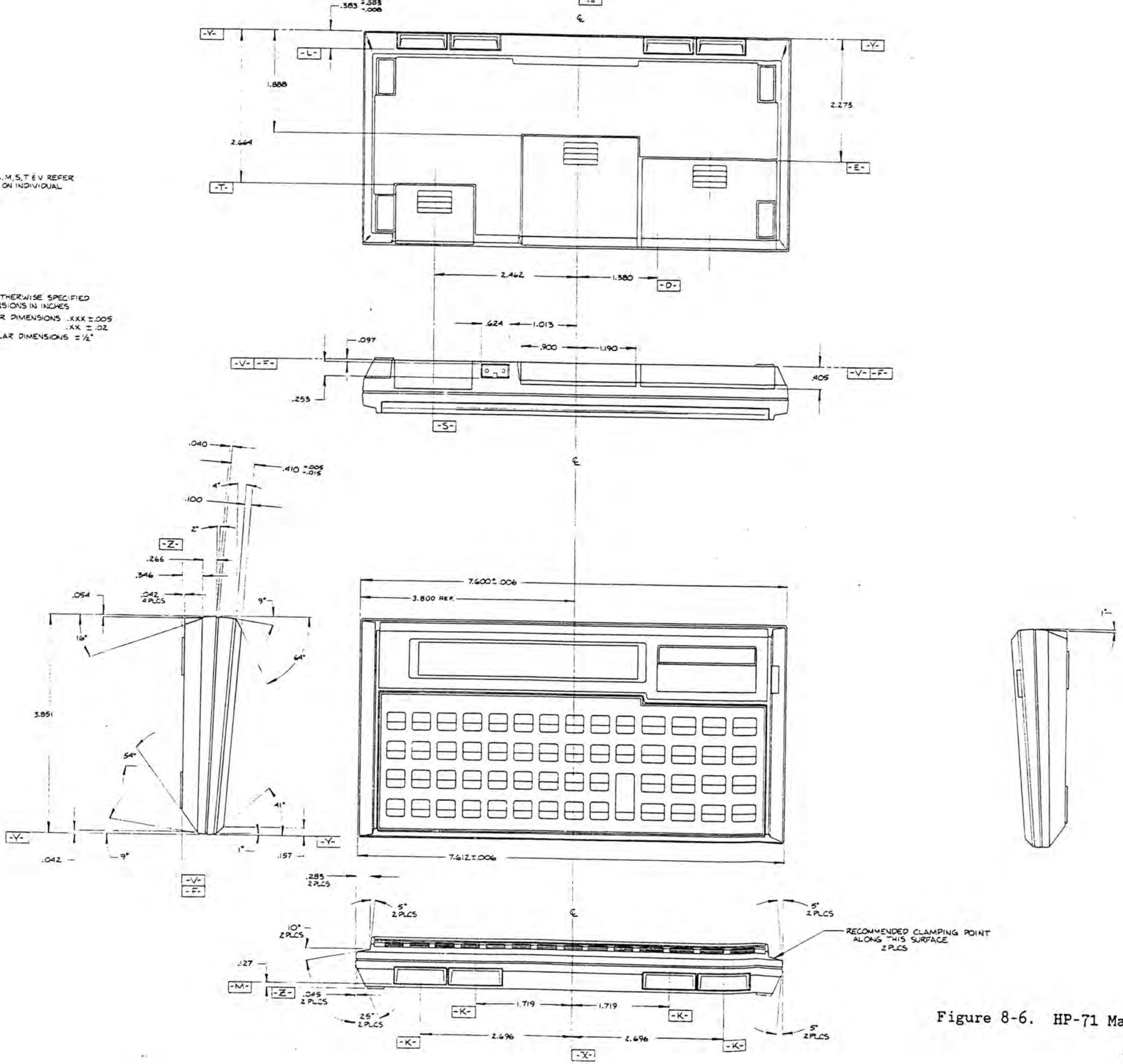
Figure 8-4. I/O PCA Component Location Diagram



NOTE 1: HPIL PORT AND PORT 3 HAVE A PAD FOR OD, BUT NORMAL MODULES WILL NOT CONTACT IT.
NOTE 2: ALL INTERCONNECTIONS ARE DRAWN IN ORDER.

PULL *INT TO GND
TO INTERRUPT

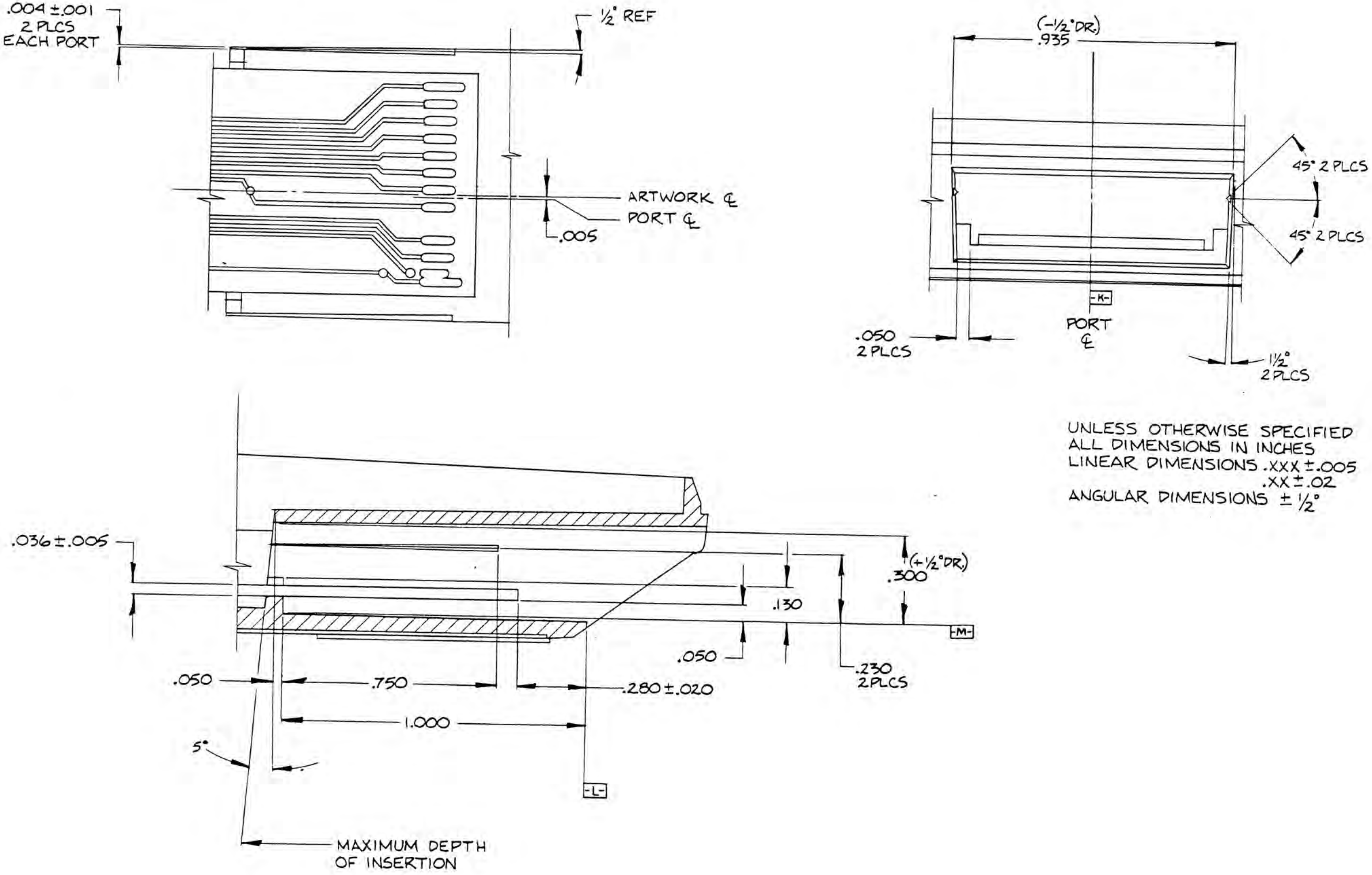
Figure 8-5. I/O PCD Sc



NOTES:
1. DATUMS D, E, F, K, L, M, S, T & V REFER TO PORT DATUMS ON INDIVIDUAL PORT DRAWINGS.

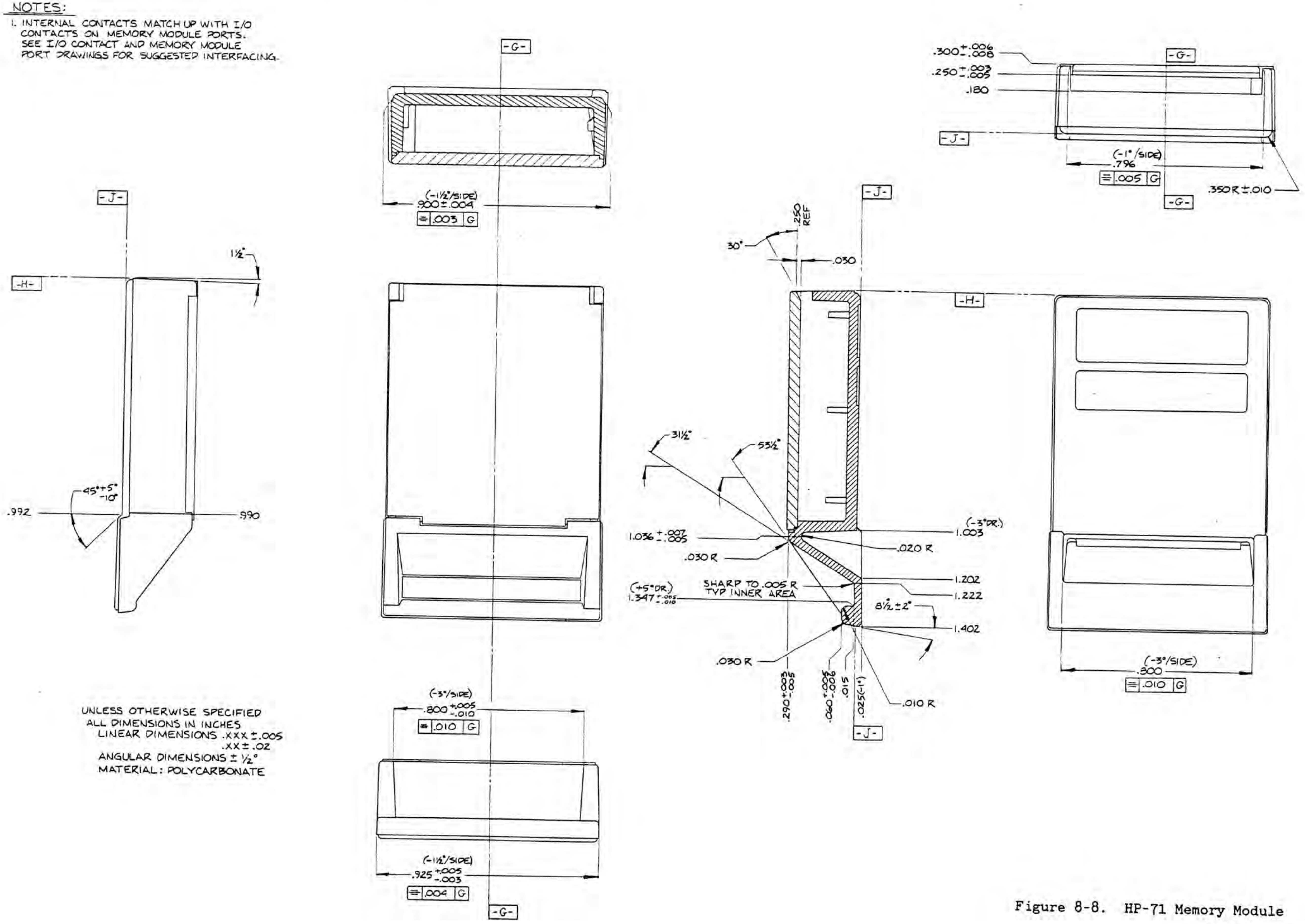
UNLESS OTHERWISE SPECIFIED
ALL DIMENSIONS IN INCHES
LINEAR DIMENSIONS .XXX ±.005
.XX ±.02
ANGULAR DIMENSIONS ±½°

Figure 8-6. HP-71 Mainframe



UNLESS OTHERWISE SPECIFIED
ALL DIMENSIONS IN INCHES
LINEAR DIMENSIONS .XXX ±.005
.XX ±.02
ANGULAR DIMENSIONS ±½°

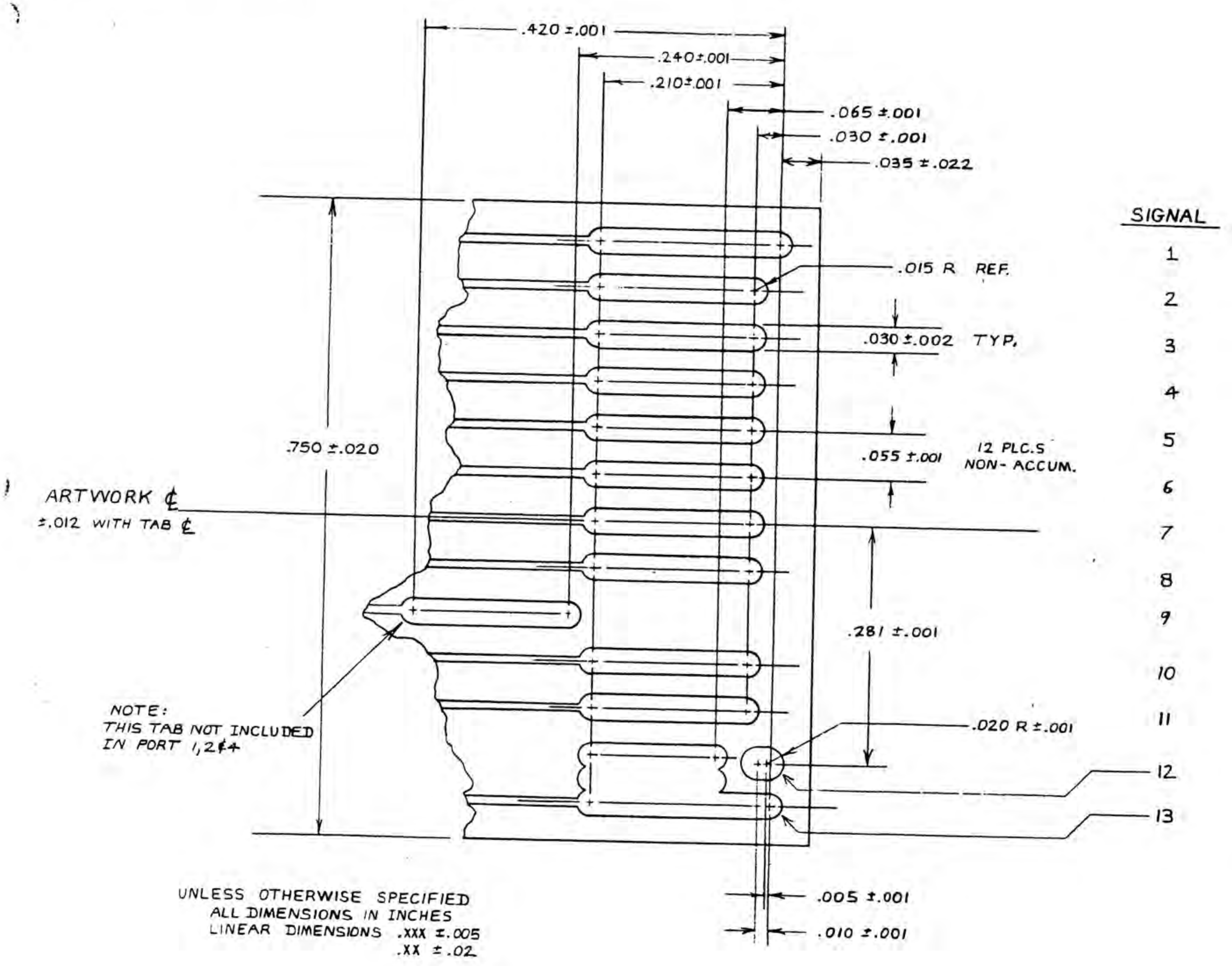
Figure 8-7. HP-71 Memory Module Port


NOTES:

1. INTERNAL CONTACTS MATCH UP WITH I/O CONTACTS ON MEMORY MODULE PORTS. SEE I/O CONTACT AND MEMORY MODULE PORT DRAWINGS FOR SUGGESTED INTERFACING.

UNLESS OTHERWISE SPECIFIED
ALL DIMENSIONS IN INCHES
LINEAR DIMENSIONS .XXX ± .005
.XX ± .02
ANGULAR DIMENSIONS ± ½°
MATERIAL: POLYCARBONATE

Figure 8-8. HP-71 Memory Module



		MEMORY				HPIL
		PORT 1	PORT 2	PORT 3	PORT 4	PORT
SIGNAL	1	VDD	VDD	VDD	VDD	VDD
	2	B3	B3	B3	B3	B3
	3	B2	B2	B2	B2	B2
	4	B1	B1	B1	B1	B1
	5	B0	B0	B0	B0	B0
	6	*STR	*STR	*STR	*STR	*STR
	7	*C/D	*C/D	*C/D	*C/D	*C/D
	8	D_{IN}/OR0	D_{IN}/OR1	D_{IN}/OR2	D_{IN}/OR3	D_{IN}
	9	—	—	OD	—	OD
	10	IR 14	IR 14	IR 14	IR 14	IR 14
	11	O.D.	HALT	HALT	HALT	HALT
	12	*INT	*INT	*INT	*INT	*INT
	13	GND	GND	GND	GND	GND

RECOMMENDED PLATING

.5 mils	COPPER CLAD
.8 mils	PLATED COPPER MIN.
.2 mils	NICKEL MIN.
.03 mils	GOLD MIN.

Figure 8-9. HP-71 I/O Contact

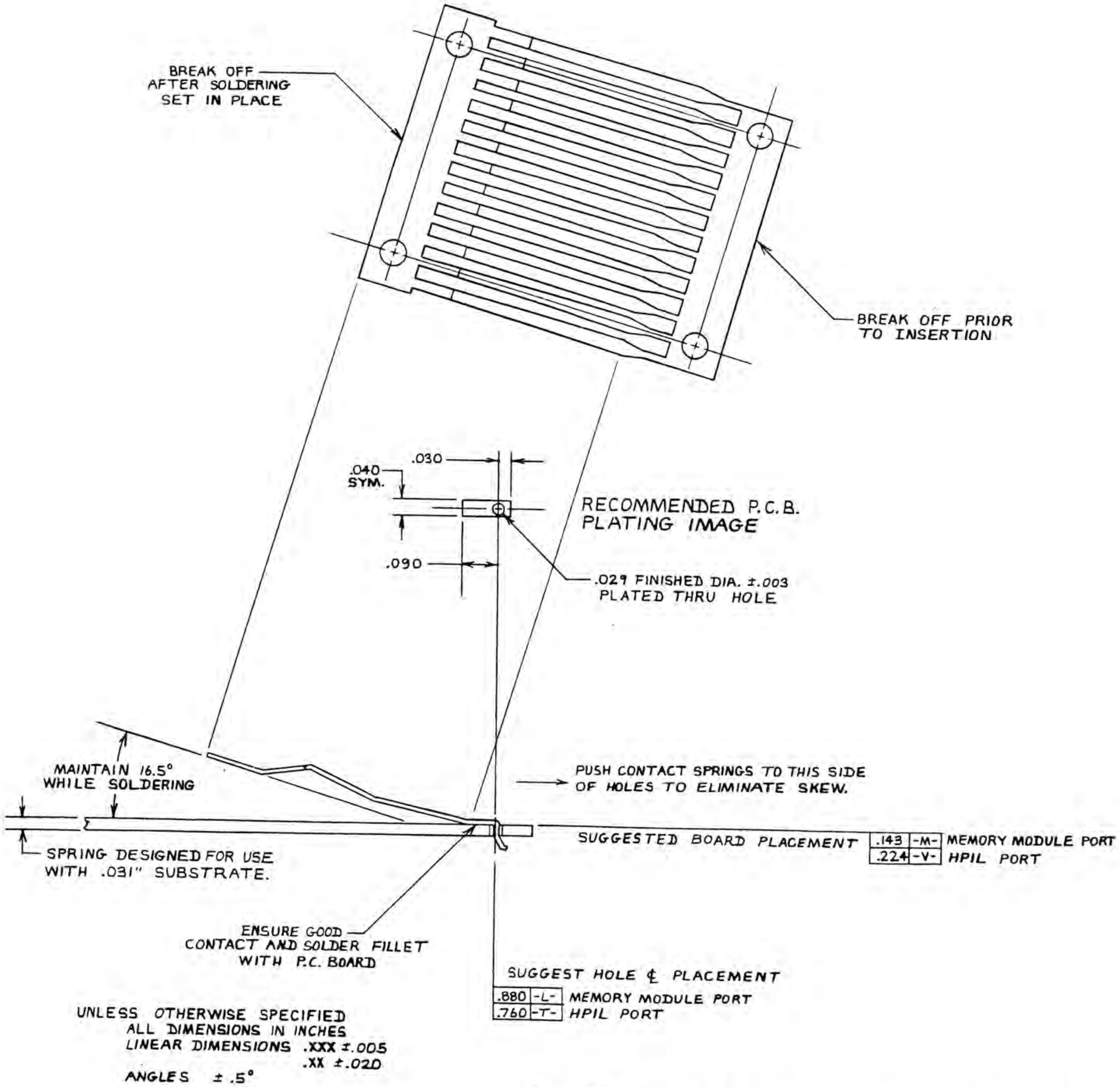


Figure 8-10. HP-71 Contact Spring Attachment Diagrams

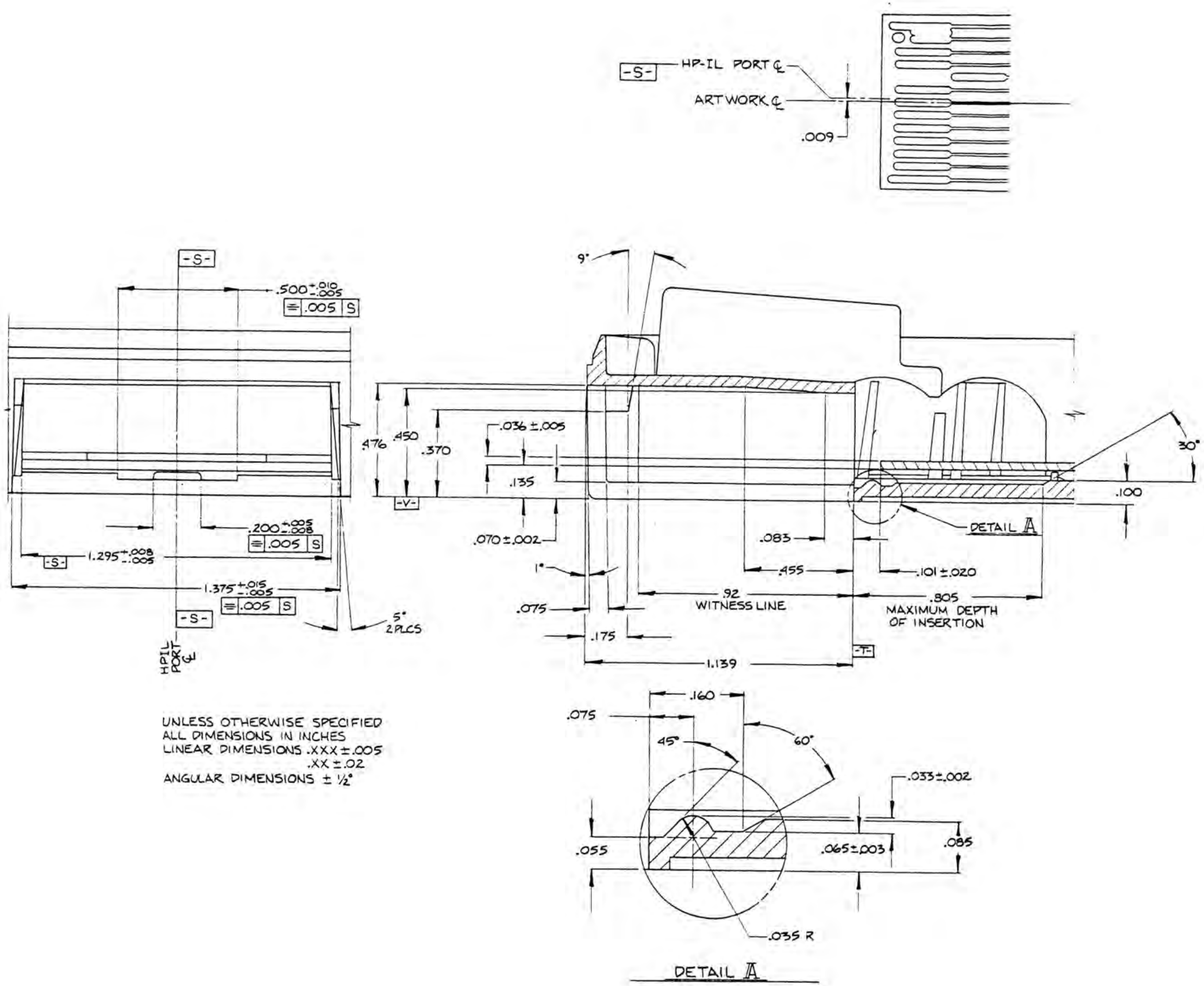
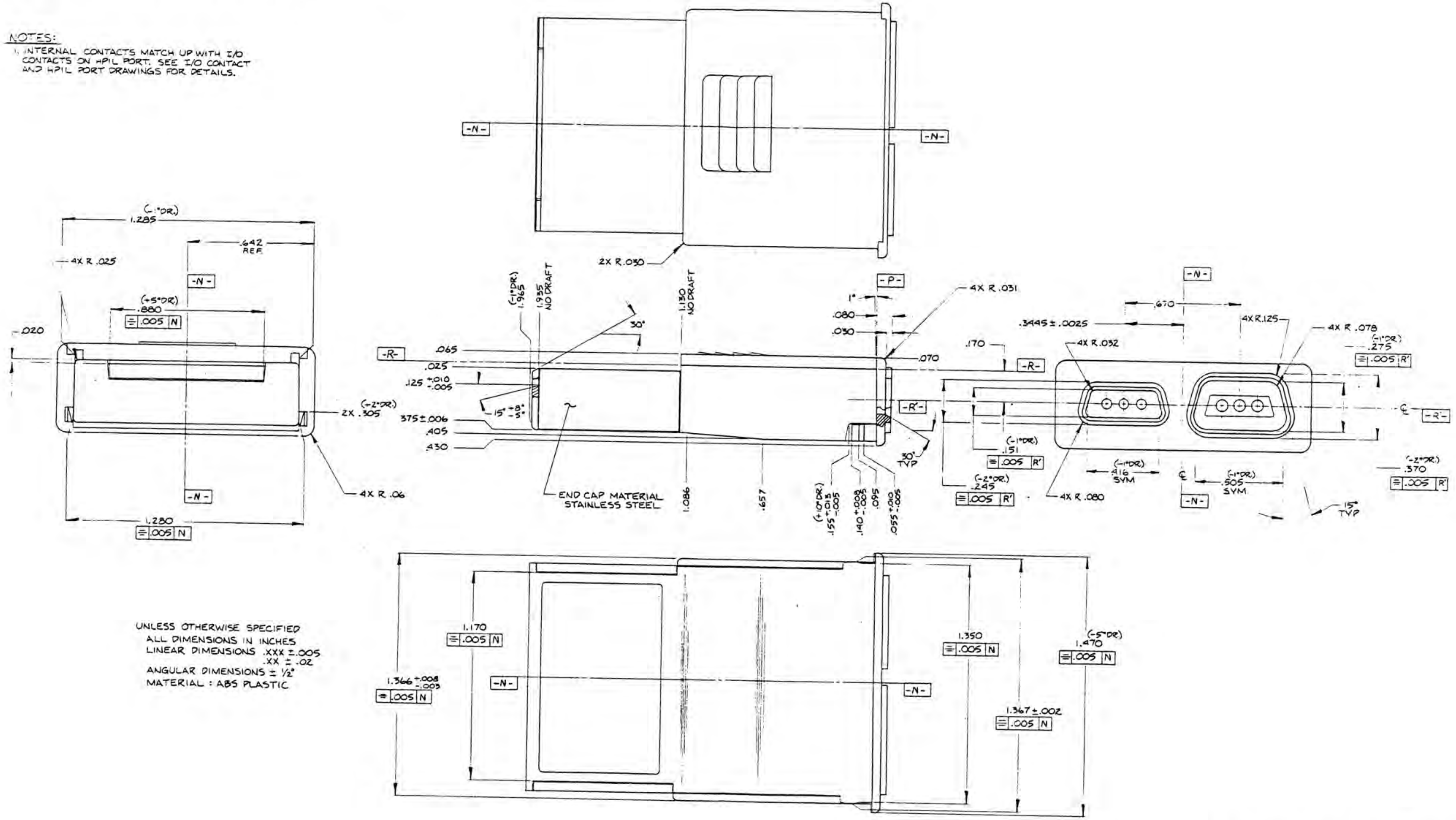


Figure 8-11. HP-71 HP-IL Module Port

NOTES:
1. INTERNAL CONTACTS MATCH UP WITH I/O CONTACTS ON HPIL PORT. SEE I/O CONTACT AND HPIL PORT DRAWINGS FOR DETAILS.



UNLESS OTHERWISE SPECIFIED
ALL DIMENSIONS IN INCHES
LINEAR DIMENSIONS .XXX ±.005
.XX ± .02
ANGULAR DIMENSIONS ± ½°
MATERIAL : ABS PLASTIC

Figure 8-12. HP-71 HP-IL Module

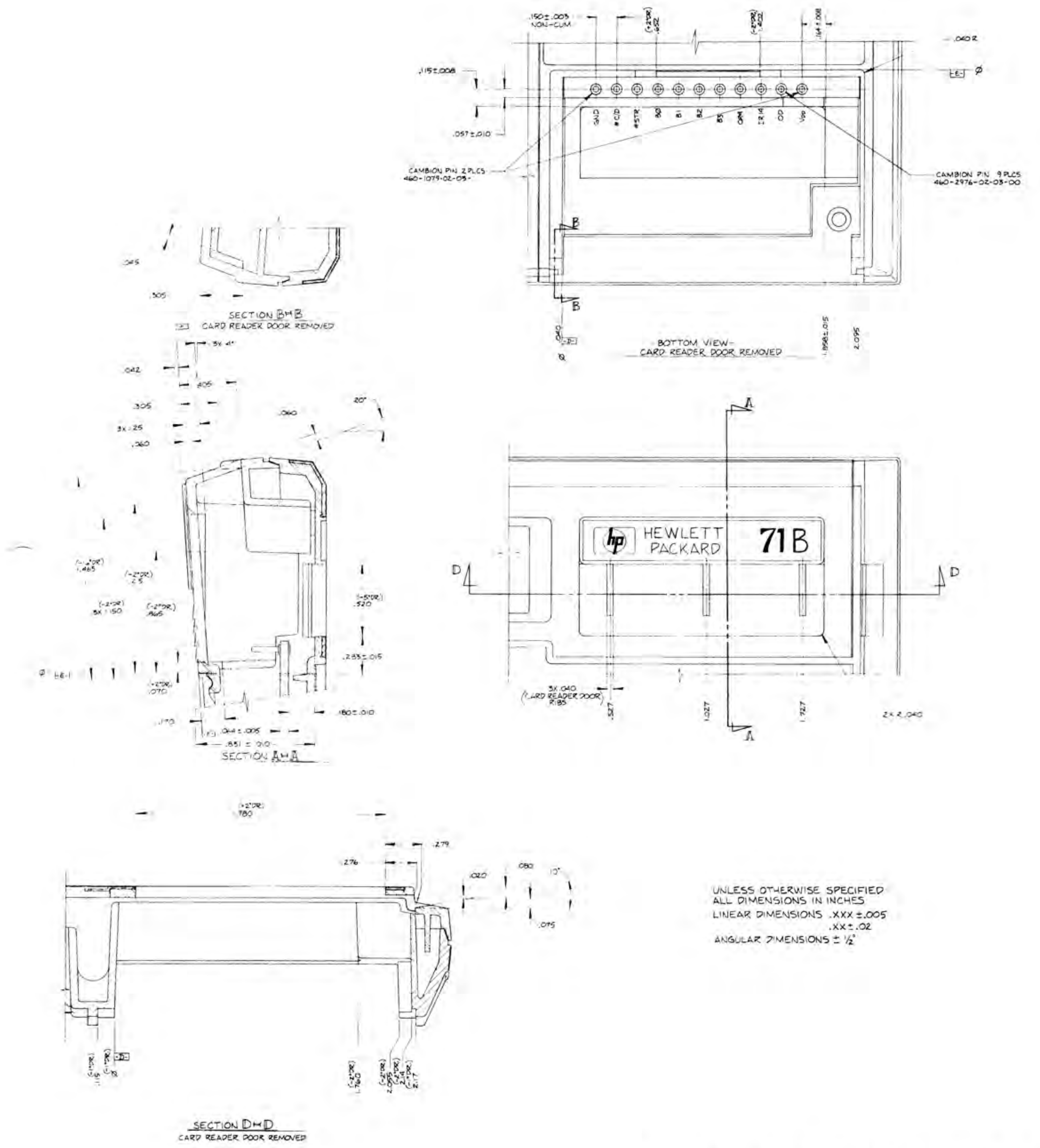


Figure 8-13. HP-71 Card Reader Port

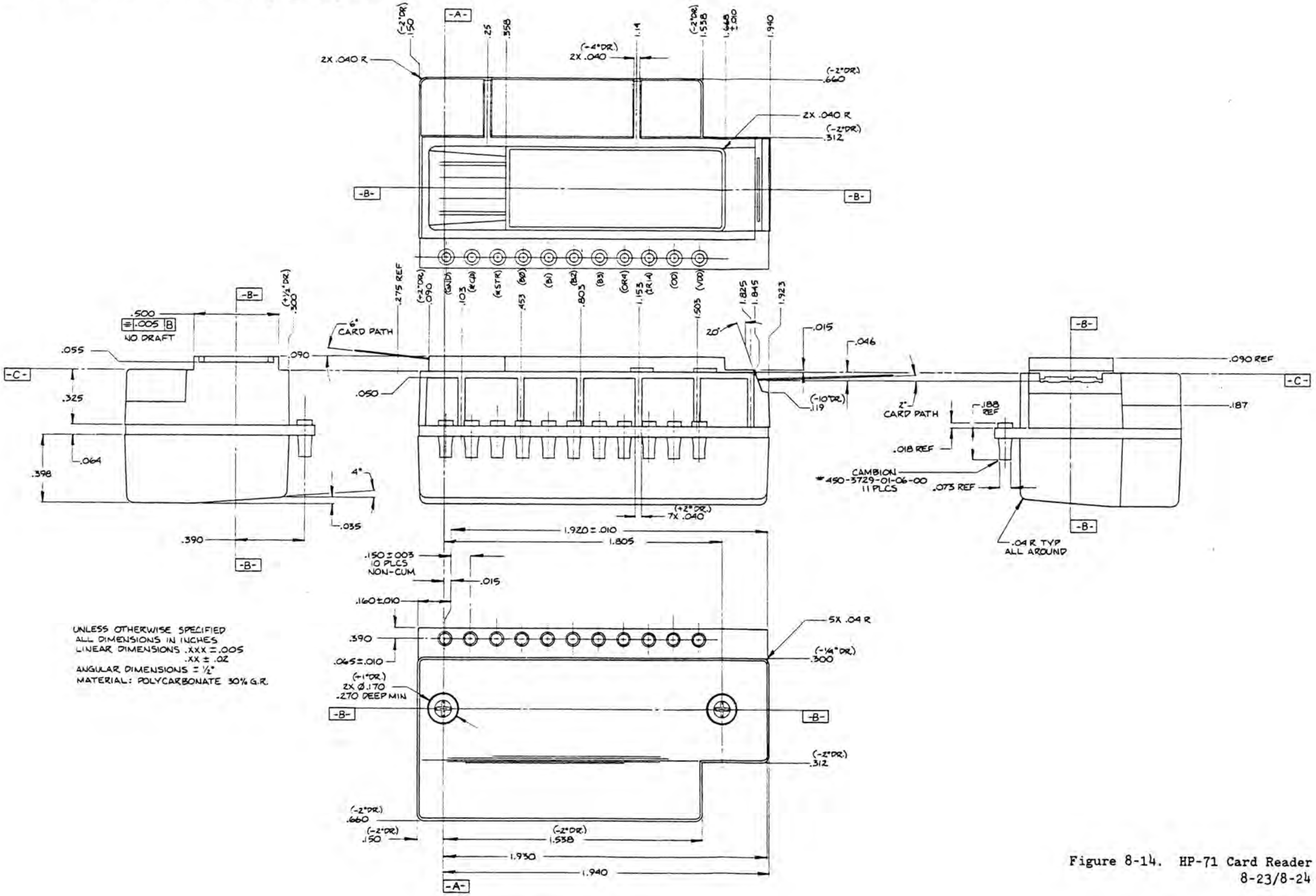


Figure 8-14. HP-71 Card Reader